CMOS LSI

8-bit Microcontroller with LCD Controller Driver 256K-byte Flash ROM / 8K-byte RAM / 100-pin



www.onsemi.com

Features

- LCD Driver 4COM × 54SEG
- Infrared Remote Control Receiver Circuit × 2
- Full duplex UART × 2

Performance

- Minimum Bus Cycle Time 56ns (CF=18MHz)
- Minimum Instruction Cycle Time (Tcyc) 167ns (CF=18MHz)
- Operating Supply Voltage 2.7[V] to 3.6[V]
- Operating Ambient Temperature -40°C to +85°C

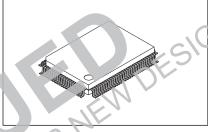
Function Descriptions

1) Ports

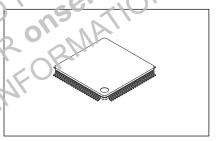
- I/O Ports
- 29
- LCD Common Ports
- 4
- LCD Segment Ports
- 54 (I/O port combined use)
- Bias Power Source For LCD
- Power Pins (VSS1, VDD1)
- 2) Timer ×
- Timer 0: 16-bit timer/counter with capture registers
- Timer 1: 16-bit timer that supports PWM/toggle outputs
- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a o-bit prescaler
- Timer 6: 8-bit time with a 6-bit prescaler (with toggle output)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer 8: 16-bit timer with an 8-bit prescaler
- Base timer
- 3) Full duplex UART \times 2
- 4) Infrared Remote Control Receiver Circuit × 2

Application

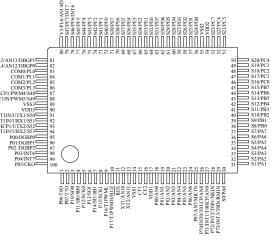
- AV apparatus
- Household appliance mounted with LCD panel



OIP100E(14X20)



TQFP100(14X14)
[Under Development]



Pin Assignment : QIP100E(14x20)
[Top view]

ORDERING INFORMATION

See detailed ordering and shipping information on page 28 of this data sheet.

* This product is licensed from Silicon Storage Technology, Inc. (USA).

Function Details

■Ports

• Normal withstand voltage I/O ports

Ports whose I/O direction can be designated in 1 bit units: 29 (P0n, P1n, P70 to P73, P8n, XT2)

• Normal withstand voltage input port: 1 (XT1)

• LCD ports

54 (S00 to S53) Segment output: Common output: 4 (COM0 to COM3) Bias power sources for LCD driver: 3 (V1 to V3)

Other functions

54 (P3n, PAn, PBn, PCn, PDn, PEn, PFn) Input/output ports:

Input ports: 7 (PLn) 2 (CF1, CF2) • Dedicated oscillator ports: • Reset pins: $1 (\overline{RES})$

• Power pins: 6 (VSS1 to VSS3, VDD1 to VDD3)

■LCD Controller

- 1) Seven display modes are available (static, 1/2, 1/3, 1/4 duty \times 1/2, 1/3 bias)
- 2) Segment output and common output can be switched to general-purpose input/output ports
- ■Small Signal Detection (MIC signals etc.)
 - 1) Counts pulses with a level which is greater than a preset value
 - 2) 2-bit counter

■Timers

- Timer 0: 16-bit timer/counter with two capture registers.
 - Mode 0: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers) × 2 channels
- gisters). Mode 1: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers) + 8-bit counter (with two 8-bit capture registers)
 - Mode 2: 16-bit timer with an 8-bit programmable prescaler (with two 16-bit capture registers)
 - Mode 3: 16-bit counter (with two 16-bit capture registers)
- Timer1: 16-bit counter timer that supports PWM/toggle outputs
 - Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer counter with an 8-bit prescaler (with toggle outputs)
 - Mode 1. 8-bit PWM with an 8-bit prescaler × 2 channels
 - Mode 2: 16-bit counter timer with an 8-bit prescaler (with toggle outputs)
 - (toggle outputs also possible from the lower-order 8 bits)
 - Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs) (The lower-order 8 bits can be used as PWM.)
- Timer4: 8-bit timer with a δ-bit prescaler
- Timer5. S-bit timer with a 6-bit prescaler
- Timer6. 8-bit timer with a 6-bit prescaler (with toggle output)
- Triner7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer8: 16-bit timer
 - Mode 0: 8-bit timer with an 8-bit prescaler \times 2 channels
 - Mode 1: 16-bit timer with an 8-bit prescaler
- Base Timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts programmable in 5 different time schemes
- Day and time counter
 - 1) Used with a base timer, the day and time counter can be used as a 65000 day + minute + second counter.

■High-speed Clock Counter

- 1) Can count clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz).
- 2) Can generate output real-time.

■ Serial Interfaces

- SIO0: 8-bit synchronous serial interface
 - 1) LSB first/MSB first made selectable
 - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle = 4/3tCYC)
 - 3) Automatic continuous data transmission (1 to 256 bits specifiable in 1-bit units, suspension and resumption of data transmission possible in 1-byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - DEORNEW DESIGN
 RORMATION
 RORMATION Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

■UART1

- Full duplex
- 7/8/9 bit data bits selectable
- 1 stop bit (2 bits in continuous data transmission)
- Built-in baudrate generator

■UART2

- Full duplex
- 7/8/9 bit data bits selectable
- 1 stop bit (2 bits in continuous data transmission)
- Built-in baudrate generator
- ■AD Converter: 12 bits × 15 channels
- ■PWM : Multi frequency 12-bit PWM × 2 channels
- Infrared Remote Control Receiver Circuit
 - 1) Noise reduction function (Time constant of noise reduction filter: approx. 120µs, when selecting a 32.768kHz crystal oscillator as a reference clock)
 - 2) Supporting reception formats with a guide-pulse of half-clock/clock/none.
 - 3) Determines a end of reception by detecting a no-signal periods (No carrier). (Supports same reception former with a different bit length.)
 - 4) X'tal HOLD mode cancellation function

■Infrared Pernote Control Receiver Circuit2

- 1) Noise reduction function
 - (Time constant of noise reduction filter: approx. 120µs, when selecting a 32.768kHz crystal oscillator as a reference clock.)
- 2) Supporting reception formats with a guide-pulse of half-clock/clock/none.
- 3) Determines a end of reception by detecting a no-signal periods (No carrier). (Supports same reception format with a different bit length.)
- 4) X'tal HOLD mode cancellation function

■Watchdog Timer

- 1) External RC watchdog timer
- 2) Interrupt and reset signals selectable

■Clock Output Function

- 1) Can output selected oscillation clock 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 as a system clock.
- 2) Can output the source oscillation clock for the sub clock.

■ Interrupt Source Flags

- 31 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

NDESIGN

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/remote control receiver1
4	0001BH	H or L	INT3/base timer/INT5/ remote control receiver2
5	00023H	H or L	T0H/INT6
6	0002BH	H or L	T1L/T1H/INT7
7	00033H	H or L	SIO0/UART1 receive/ UART2 receive/T8L/T8H
8	0003BH	H or L	SIO1/UART1 transmit/ UART2 transmit
9	00043H	H or L	ADC/MIC/T6/T7/PWM4/PWM5
10	0004BH	H or L	Port 0/T4/T5

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- IFLG (List of interrupt source flag function)
 - 1) Shows a list of interrupt source flags that caused a branching to a particular vector address routine Stack Levels
 096/2048 levels maximum (The stack is allocated in RAM.)

■Subroutine Stack Levels

- 4096/2048 levels maximum (The stack is allocated in RAM.
- ■High-speed Multiplication/Division Instructions
 - 16 bits × 8 bits (5 tCYC execution time)
 - 12 tCYC execution time) • 24 bits × 16 bits
 - 16 bits ÷ 8 bits 8 tCYC execution time)
 - 24 bits ÷ 16 bits (12 tCYC execution time

■Oscillation Circuits

- RC oscillation circuit (internal): For system clock
- CF oscillation circuit: For system clock, with internal Rf and external Rd
- Crystal oscillat on circuit: For low-speed system clock, with internal Rf and external Rd
- Multifrequency RC oscillation circuit (internal): For system clock
 - 1) Adjustable in $\pm 4\%$ (typ) increments from the selected center frequency.
 - 2) Measures the frequency of the source oscillation clock using the input signal from XT1 as the reference.

System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2μs, 2.4μs, 4.8μs, 9.6μs, 19.2μs, 38.4μs, and 76.8µs (at a main clock rate of 10MHz).

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation (Some parts of the serial transfer function stop operation).
 - 1) Oscillation is not stopped automatically.
 - 2) Canceled by a system reset or occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC, X'tal, and multifrequency RC oscillators automatically stop operation.
 - 2) There are three ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Setting at least one of the INT0, INT1, INT2, INT4, and INT5 pins to the specified level
 - (3) Having an interrupt source established at port 0
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer and infrared remote controller circuit.
 - 1) The CF, RC, and multifrequency RC oscillators automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are five ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Setting at least one of the INT0, INT1, INT2, INT4, and INT5 pins to the specified level
 - (3) Having an interrupt source established at port 0
 - (4) Having an interrupt source established in the base timer circuit
 - (5) Having an interrupt source established in the infrared remote control receives circuit.

■On-chip Debugger Function

• Supports software debugging with the IC mounted on the target board.

■Package Form

- QIP100E(14×20) : Pb-Free/Halogen Free type
- TQFP100(14×14) : Pb-Free/Halogen Free type [Under Development]

■Development Tools

• On-chip Debugger: TCB87 TypeB +LC87F7Nxx A or TCB87 TypeC (3Lines Cable) +LC87F7NxxA

■Flash ROM Programming boards

Package	Programming Boards
QIP100E(14×20)	W87FQ100
TQFP100(14×14)	W87FSQ100

■Flash ROM Programmer

Maker		Model	Supported Version	Device
	Single Programmer	AF9709C	(Note 2)	LC87F7NP6A LC87F7NJ2A LC87F7NC8A
Flash Support Group, Inc (FSG)	Gang	AF9723/AF9723B(main unit) (including models manufactured by Ando Electric Co., Ltd.)	(Note 2)	LC87F7NP6A
	Programmer	AF9833(unit) (including models manufactured by Ando Electric Co., Ltd.)	(Note 2)	LC87F7NJ2A LC87F7NC8A
Flash Support Group, Inc (FSG) +Our company (Note 1)	In-circuit Single/Gang Programmer	AF9101/AF9103(main unit) (manufactured by FSG) SIB87 Type C (Interface Driver) (Our company model)	(Note 2)	LC87F7NP6A LC87F7NJ2A LC87F7NC8A
Our company	Single/Gang Programmer In-circuit Single/Gang Programmer	SKK Type b / Type C (SanyoFV/S) SKK-DBG Type B /Type C (SanyoFWS)	Application Version 1.08or later Chip Data Version 2.4 later	LC27F7NP6A LC87F7NJ2A LC87F7NC8A

Contact information about the AF series:

ontact information about the AF series:
Flash Support Group Company (TOA ELF TRONICS Inc.)

E-mail: sales@j-fsg co.j

Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from our company (SIB87) together can give a PC-less, standalone on-board-programming capabilities.

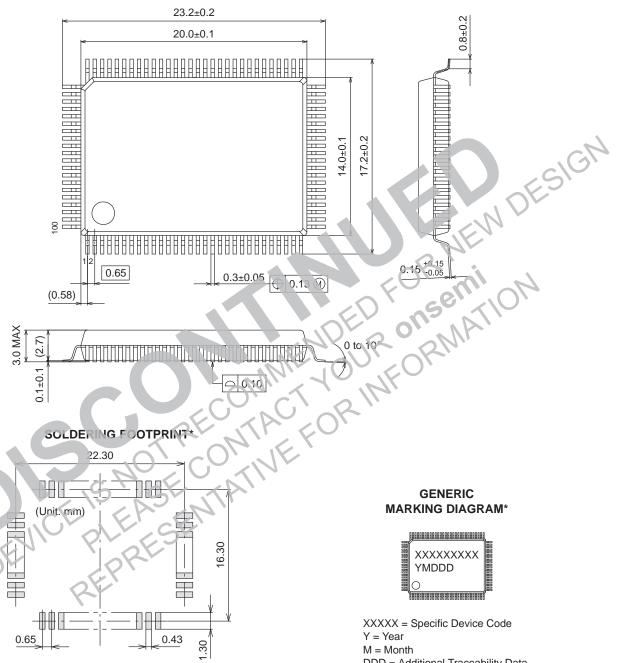
Note2: It needs a special programming devices and applications depending on the use of programming environment. THIS DEVICE REPRESE Plene ask FSG or our company for the information.

Package Dimensions

unit: mm

PQFP100 14x20 / QIP100E

CASE 122BV ISSUE A



NOTE: The measurements are not to guarantee but for reference only.

DDD = Additional Traceability Data

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■ ", may or may not be present.

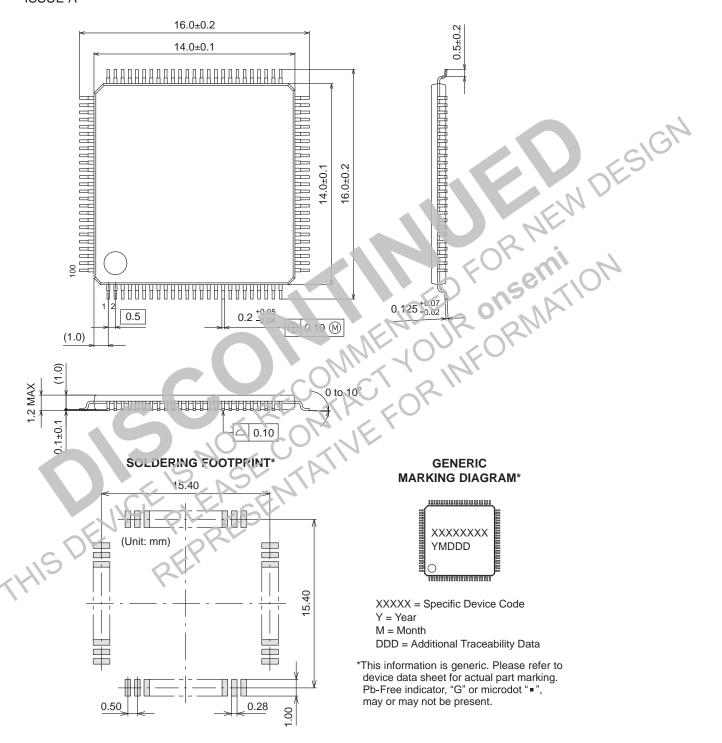
Package Dimensions

unit: mm

*Package TQFP100(14×14) type is Under Development.

TQFP100 14x14 / TQFP100

CASE 932AY ISSUE A

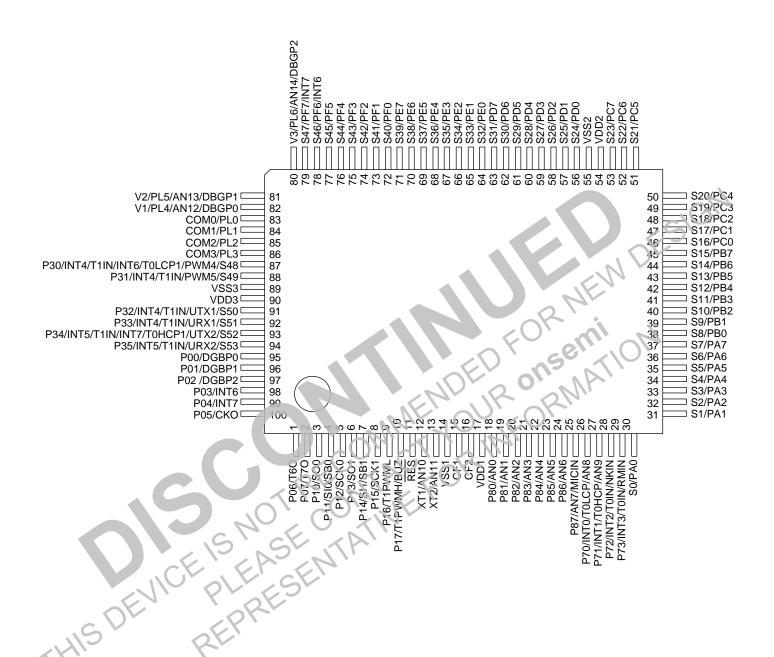


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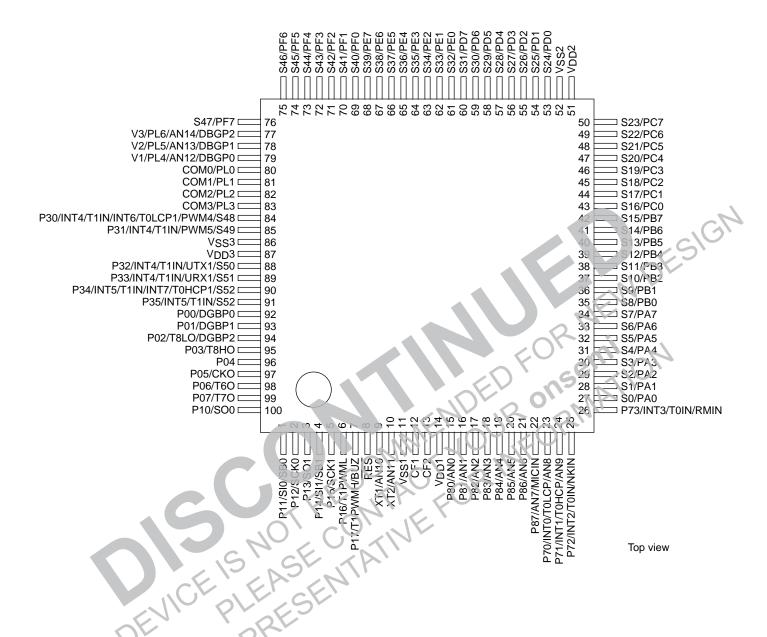
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Pin Assignment

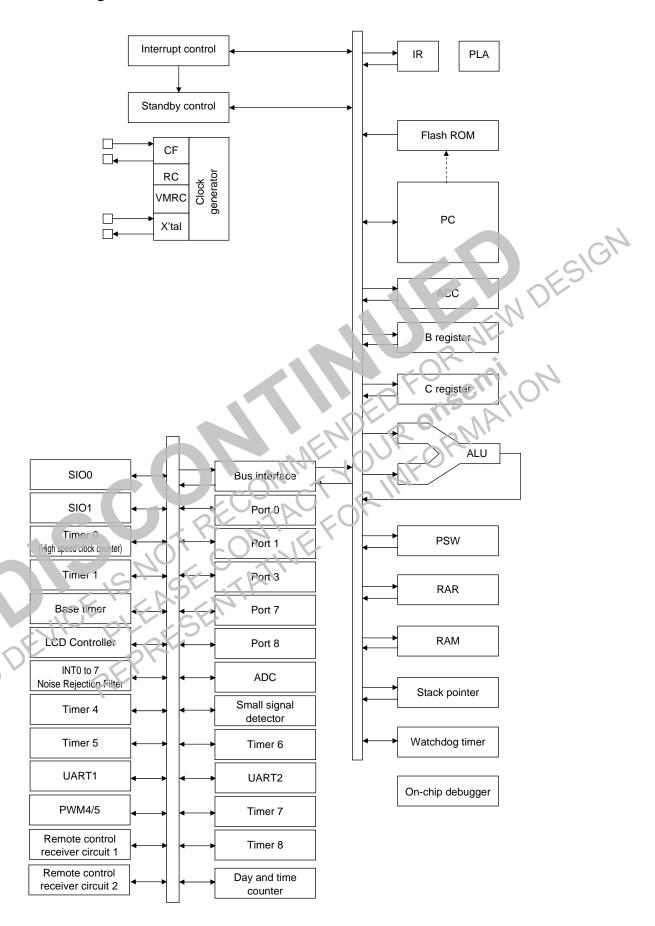
QIP100E(14×20), Pb-Free/Halogen Free type



TQFIP100(14×14), Pb-Free/Halogen Free type [Under Development]



System Block Diagram



Pin Description

Pin Name	I/O			D	escription			Option
V _{SS} 1	-	- power sup	ply pin					No
V _{SS} 2								
V _{SS} 3								
V _{DD} 1	-	+ power sup	pply pin					No
V _{DD} 2								
V _{DD} 3								
Port 0	I/O	• 8-bit I/O po	ort					Yes
P00 to P07			able in 1-bit units					
F00 t0 F07			sistors can be turn	ed on and off in 1	-bit units			
		-	OLD release					
		•	ort 0 interrupt					
		Shared pir	•					
		P03: INT6						
		P04: INT7	•					
			coutput (system c	lock/can selected	I from sub clock)			
			r 6 toggle output	noon can scicotec	THOM SUB CIOCK)			-\(\frac{1}{2}\)
								151
			r 7 toggle output	CDO to DBCD2/D	00 to P02)			
Port 1	I/O	8-bit I/O po	ebugger pins: DB0	51 0 to DBGF2(Pt	00 10 F 02)			Yes
	1,0	•	able in 1-bit units					165
P10 to P17		•	sistors can be turn	ed on and off in 1	-bit units			
		Shared pir		ed on and on in i	-bit utilits.		NV	
		•	data output				2,	
			data input/bus I/0), "	
		P12: SIO0	•				0.	
			data output				35° 1\	
			data input/bus I/0				" DI	
		P15: SIO1				.02	ONLI	
			r 1PWML output			1/1/	15/1.	
			r 1PWMH output/	neeper output) < (RMATI RMATI	
Port 3	I/O	• 6-bit 1/O po		beeder output	· · · · · · · · · · · · · · · · · · ·	16.		Yes
	1/0		output for LCD			111-		103
P30 to P35			ble in 1-bit units					
			istors can be turn		-hit units			
		Shared pin		od on and on in 1	Dit di ilici			
				D release input/ti	ne 1 event innut	t/timer 0L capture	input/	
		30 10 1 3	timer 0!1 captur		Tier i event inpu	viinici or capiaic	прав	
		P34 to P34			mer 1 event innut	t/timer 0L capture	input/	
		1 04101 00	timer oH captur		mer reventinpu	vanier of capture	прав	
	CX	P30: P\//\/	14 output/INTS inp		re 1 innut			
	1/0	P31: PWN		autimor of oapta	io i ilipat			
	11,		(1) transmit					
OK		P33: UAR						
CV			Γ2 transmit/INT7 i	nnut/timer 0H car	ature 1 input			
7/3	1	P37: UAR		inpagainiei oi i cap	input			
AIS DE			nowledge type					
					Rising &			
			Rising	Falling	Falling	H level	L level	
		INT4	enable	enable	enable	disable	disable	
		INT5	enable	enable	enable	disable	disable	
•	1			enable		disable	disable	
		IIVIn	enanie		enanie			
		INT6 INT7	enable enable	enable	enable enable	disable	disable	

Continued on next page.

Continued from preceding page.

Pin Name	1/0	Description	Option
Port 7	I/O	• 4-bit I/O port	No
P70 to P73		• I/O specifiable in 1-bit units	
17010173		Pull-up resistors can be turned on and off in 1-bit units.	
		• Shared pins	
		P70: INT0 input/HOLD release input/timer 0L capture input/watchdog timer output	
		P71: INT1 input/HOLD release input/timer 0H capture input	
		P72: INT2 input/HOLD release input/timer 0 event input/timer 0L capture input/	
		high speed clock counter input	
		P73: INT3 input (with noise filter)/timer 0 event input/timer 0H capture input/	
		remote control receiver input	
		AD converter input ports: AN8 (P70), AN9 (P71)	
		Interrupt acknowledge type	
		Rising &	
		Rising Falling Falling H level L level	
		INTO enable enable disable enable enable	
		INT1 enable enable disable enable enable	. (
		INT2 enable enable enable disable disable	G
		INT3 enable enable enable disable disable	(2)
			OV
Port 8	I/O	• 8-bit I/O port	No
P80 to P87		• I/O specifiable in 1-bit units	0
		Shared pins	
		AD converter input ports: AN0 to AN7	
		Small signal detector input port: MICIN (P87)	
S0/PA0 to	I/O	Segment output for LCD	No
S7/PA7		Can be used as general-purpose 1/O port (PA)	
S8/PB0 to	I/O	Segment output for LCD	No
S15/PB7	1,0	Can be used as general-purpose I/O port (PB).	140
S16/PC0 to	I/O	Segment output for LCD.	No
	1/0		INO
S23/PC7	1/0	Can be used as general-purpose I/O port (PC)	
S24/PD0 to	I/O	Segment output for LCD	No
S31/PD7		Can be used as general-purpose I/O port (PD)	
S32/PE0 to	I/O	Segment output for LCD	No
S39/PE7		Can be used as general purpose I/O port (PL)	
S40/PF0 to	1/0	Segment output for LCD	No
S47/PF7		Can be used as general-purp se I/O port (PF)	
		PF6: INT6 input	
		PF7: IN17 input	
COMO/PL0 to	1/0	Common output for LCD	No
COM3/PL3		Can be used as general-purpose input port (PL)	
V1/PL4 to	I/O	• LCD output bias power supply	No
V3/PL6		Can be used as general-purpose input port (PL)	
		• Shared pins	
		AD converter input ports: AN12 (V1) to AN14 (V3)	
115		On-chip debugger pins: DBGP0 (V1) to DBGP2 (V3)	
RES	Input	Reset pin	No
XT1		•	
XII	Input	32.768kHz crystal oscillator input pin	No
		Shared pins	
		General-purpose input port	
		Must be connected to V _{DD} 1 if not to be used.	
		AD converter input port: AN10	
XT2	I/O	32.768kHz crystal oscillator output pin	No
		Shared pins	
		General-purpose I/O port	
		Must be set for oscillation and kept open if not to be used.	
		AD converter input port: AN11	
CF1	Input	Ceramic resonator input pin	No
CF2		Ceramic resonator output pin	
01.2	Output	Gerannic resonator output piri	No

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode

Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	each bit	1	CMOS	Programmable (Note)
		2	Nch-open drain	Programmable
P10 to P17	each bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P30 to P35	each bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
P80 to P87	-	No	Nch-open drain	No
S0/PA0 to S47/PF7	-	No	CMOS	Programmable
COM0/PL0 to COM3/PL3	-	No	Input only	No GC
V1/PL4 to V3/PL6	-	No	Input only	No
XT1	-	No	Input only	No
XT2	-	No	Output for 32.768kHz crystal oscillator (Nch-open drain when in general-purpose output mode)	No

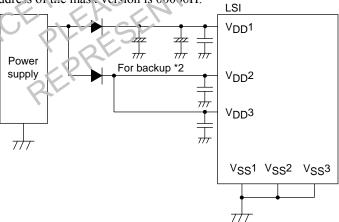
User Option List

THIS DE

User Option L	User Option List								
Option Name	Option Type	Mask Version *1	Flash Version	Option Selected in Units of	Specified Item				
	P00 to P07	0	OF	each oit	CMOS No r-open drain				
Port output form	P10 to P17	0	c		CMOS Nch-open drain				
	P30 to P35)	each bit	CMOS				
	F30 10 F33	25		each bit	Nch-open drain				
Program start		×	The state of the s		00000H				
address		*2		-	1FF00H				

^{*1:} Mask option selection - No change possible after the mask is completed.

*2: Program start address of the mask version is 00000H.



- *1: Connect the IC as shown below to minimize the noise input to the VDD1 pin. Be sure to electrically short the VSS1, VSS2, and VSS3 pins.
- *2: The internal memory is sustained by $V_{DD}1$. If none of $V_{DD}2$ and $V_{DD}3$ are backed up, the high level output at the ports are unstable in the HOLD backup mode, allowing through current to flow into the input buffer and thus shortening the backup time.

Make sure that the port outputs are held at the low level in the HOLD backup mode.

Absolute Maximum Ratings at $\mathrm{Ta} = 25^{\circ}\mathrm{C},\, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

	D	0		0, 15,51			Specif	ication	
	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Ма	ximum supply voltage	V _{DD} max	$V_{DD}1$, $V_{DD}2$, $V_{DD}3$	$V_{DD}1=V_{DD}2=V_{DD}3$		-0.3		+4.6	
su LC	pply voltage for D	VLCD	V1/PL4, V2/PL5, V3/PL6	$V_{DD}1=V_{DD}2=V_{DD}3$		-0.3		V_{DD}	
Inp	out voltage	V _I (1)	Port L XT1, CF1, RES			-0.3		V _{DD} +0.3	V
		V _I (2)	V_{DD}^{2}, V_{DD}^{3}			V_{SS}		V _{DD} +0.1	
Inp	out/output voltage	V _{IO} (1)	Ports 0, 1, 3, 7, 8 Ports A, B, C, D, E, F, XT2			-0.3		V _{DD} +0.3	
	Peak output current	IOPH(1)	Ports 0, 1, 32 to 35	CMOS output selected Current at each pin		-10			
		IOPH(2)	Ports 30, 31	CMOS output selected Current at each pin		-20			
		IOPH(3)	Ports 71 to 73	Current at each pin		-5			
		IOPH(4)	Ports A, B, C, D, E, F	Current at each pin		-5			~1(·
rent	Mean output current	IOMH(1)	Ports 0, 1, 32 to 35	CMOS output selected Current at each pin		-7.5		OE	5
High level output current	(Note 1-1)	IOMH(2)	Ports 30, 31	CMOS output selected Current at each pin		-15		1	
l out		IOMH(3)	Ports 71 to 73	Current at each pin		-3			
leve		IOMH(4)	Ports A, B, C, D, E, F	Current at each pin		-3			
ligh	Total output	ΣΙΟΑΗ(1)	Ports 0, 1, 32 to 35	Total of all pins		-25	10-	- \	
_	current	ΣΙΟΑΗ(2)	Ports 30, 31	Total of all pins		-25			
		ΣΙΟΑΗ(3)	Ports 0, 1, 3	Total of all pins	<u> </u>	-45		/O	
		ΣΙΟΑΗ(4)	Ports 71 to 73	Total of all pins					
		ΣΙΟΑΗ(5)	Ports A, B. C	Total of all pins	10	- 25	7/1		
		ΣΙΟΑΗ(6)	Ports D, E, F	Total of all pins	40)	-25 -25			
		ΣΙΟΑΗ(7)	Ports A, B, C, D, E, F	Total of all pins		-25 -45			
	Peak output	IOPL(1)	Ports 0, 1, 32 to 35	Current at each pin	-127,	-43		20	mA
	current	IOPL(2)	Ports 30, 31	Current at each pin	2 /			20	
		IOPL(3)	Ports 7, 8	Current at each pin				10	
		IOPL(4)	ΛΓ2 Ports A, F, C, D, E F	Current at each pin				40	
	Mean output	IOML(1)	Ports 0, 1, 32 to 35	Current at each pin				10	
Ę	current	IOML(2)	Ports 30, 31	Current at each pin				15	
Low level output current	(Note 1-1)	iOi/L(3)	Forts 7, 8	Current at each pin				7.5	
outp		IOML(4)	Ports A, B, C, D, E, F	Current at each pin				7.5	
evel	Total ou pur	ΣOAL(1)	Pons 0,1,32 to 35	Total of all pins				45	
e we	current	$\Sigma IOAL(2)$	Forts 30, 31	Total of all pins				45	
Z	3	ΣΙΟΑL(3)	Ports 0, 1, 3	Total of all pins				80	
		ΣΙΟΑL(4)	Ports 7, 8	Total of all pins				20	
		ΣIOAL(5)	XT2 Ports A, B, C	Total of all pins				45	
		ΣΙΟΛ L (6)	Ports D, E, F	Total of all pins				45	
		ΣΙΟΛ L (0)	Ports A, B, C, D, E, F	Total of all pins				80	
Ms	l aximum power	Pd max	QIP100E(14×20)	Ta=-40 to +85°C				215	
	sipation	I G IIIAX	TQFP100(14×14)	Ta=-40 to +85°C				TBD	mW
	perating ambient	Topr	1901 100(17/14)	14- 10 to 100 0				עמו	
	nperature	ιορι				-40		+85	
	orage ambient	Tstg							°C
	mperature	_				-55		+125	

Note 1-1: The mean output current is a mean value measured over 100ms.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Allowable Operating Range at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symbol	Pin/Remarks	Conditions			Specifi	cation	
i alametei	Symbol	1 III/IVemans	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	$V_{DD}1=V_{DD}2=V_{DD}3$	0.167μs≤tCYC≤200μs		2.7		3.6	
supply voltage (Note 2-1)			0.356μs≤tCYC≤200μs		2.5		3.6	
Memory sustaining supply voltage	VHD	V _{DD} 1	RAM and register contents sustained in HOLD mode.		2.0		3.6	
High level input voltage	V _{IH} (1)	Ports 0, 3, 8 Ports A, B, C, D, E, F Port L	Output disabled	2.5 to 3.6	0.3V _{DD} +0.7		V_{DD}	
	V _{IH} (2)	Port 1 Ports 71 to 73 P70 port input/ interrupt side	Output disabled When INT1VTSL=0 (P71 only)	2.5 to 3.6	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (3)	P71 interrupt side	Output disabled When INT1VTSL=1	2.5 to 3.6	0.85V _{DD}		V _{DD}	·C
	V _{IH} (4)	P87 small signal input side	Output disabled	2.5 to 3.6	0.75V _{DD}		VDD	31
	V _{IH} (5)	P70 watchdog timer side	Output disabled	2.5 to 3.6	0.9V _{DD}		V _{DD}	V
	V _{IH} (6)	XT1, XT2, CF1, RES		2.5 to 3.6	0.75V _{DD}	7E	V_{DD}	
Low level input voltage	V _{IL} (1)	Ports 0, 3, 8 Ports A, B, C, D, E, F Port L	Output disabled	2.5 to 3.6	V _{SS}	mi	0.2V _{D,O}	
	V _{IL} (2)	Port 1 Ports 71 to 73 P70 port input/ interrupt side	Output disabled When INT1VTSL=0 (P71 only)	2.5 to 3.6	V _{SS}	NAT	0.2V _{DD}	
	V _{IL} (3)	P71 interrupt side	Output disablea Wnen INT1VTSL=1	2.5 to 3.6	V _{SS}		0.45V _{DD}	
	V _{IL} (4)	P87 small signal input side	Output disal led	2.5 to 3.6	V _{SS}		0.25V _{DD}	
	V _{IL} (5)	P70 watchdog timer	Output disabled	2.5 to 3.6	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (ô)	XT1, XT2, CF1 RES	CO. 41/2	2.5 to 3.6	V _{SS}		0.25V _{DD}	
Instruction cycle	tCYC	(S) GV	. K \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	2.7 to 3.6	0.167		200	
time (Note 2-2)	CE	CAS	H.	2.5 to 3.6	0.356		200	μS
External system clock frequer cv	FEXOF(1)	EPRESI	CF2 pin open System clock frequency division ratio=1/1 External system clock duty=50±5%	2.5 to 3.6	0.1		18	MHz
			CF2 pin open System clock frequency division ratio=1/2	2.5 to 3.6	0.2		36	

Note 2-1: V_{DD} must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Continued on next page.

Continued from preceding page.

Parameter	Symbol	Pin/Remarks	Conditions			Specifi	cation			
Parameter	Symbol	Pin/Remarks	V _E		min	typ	max	unit		
Oscillation frequency range	FmCF(1)	CF1, CF2	18MHz ceramic oscillation See Fig. 1.	2.7 to 3.6		18				
(Note 2-3)	FmCF(2)	CF1, CF2	8MHz ceramic oscillation See Fig. 1.	2.5 to 3.6		8				
_	FmRC		Internal RC oscillation	2.5 to 3.6	0.3	1.0	2.0			
	FmVMRC(1)		 Frequency variable RC source oscillation When VMRAJ2 to 0=4, VMFAJ2 to 0=0, VMSL4M=0 	2.5 to 3.6		10	MHz			
	FmVMRC(2)		 Frequency variable RC source oscillation When VMRAJ2 to 0=4, VMFAJ2 to 0=0, VMSL4M=1 	2.5 to 3.6		4		3\C		
	FsX'tal	XT1, XT2	• 32.768kHz crystal oscillation • See Fig. 2.	2.5 to 3.6		32.768	100	kHz		
Frequency	OpVMRC(1)		When VMSL4M=0	2.5 to 3.6	8	10	12			
variable RC oscillation usable range	OpVMRC(2)		When VMSL4M=1	2.5 to 3.6	3.5	4	4.5	MHz		
Frequency variable RC	VmADJ(1)		Each step of vMRAJn (Wide range)	2.5 to 3.6	88	24	64			
oscillation adjustment range	VmADJ(2)		Each step of VMFAJn (Small range)	2.5 to 3.6	0110	4	8	%		

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Electrical Characteristics at $Ta = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0\text{V}$

	O. male 1		Contribution of		Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
High level input	I _{IH} (1)	Ports 0, 1, 3, 7, 8	Output disabled						
current	GV.	Ports A. B, C, D. E	Pull-up resistor off	2.5 to 3.6			1		
		Port	 V_{IN}=V_{DD} (Including output Tr's off leakage current) 						
	I _{IH} (2)	RES	V _{IN} =V _{DD}	2.5 to 3.6			1		
115	I _{IH} (3)	XT1, XT2	 For input port specification V_{IN}=V_{DD} 	2.5 to 3.6			1		
	I _{IH} (4)	CF1	V _{IN} =V _{DD}	2.5 to 3.6			15		
	I _{IH} (5)	P87 small signal input side	V _{IN} =VBIS+0.5V (VBIS: Bias voltage)	2.5 to 3.6	1.5	5.5	10		
Low level input current	I _{IL} (1)	Ports 0, 1, 3, 7, 8 Ports A, B, C, D, E, F Port L	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.5 to 3.6	-1			μА	
	I _{IL} (2)	RES	V _{IN} =V _{SS}	2.5 to 3.6	-1				
	I _{IL} (3)	XT1, XT2	 For input port specification V_{IN}=V_{SS} 	2.5 to 3.6	-1				
	I _{IL} (4)	CF1	V _{IN} =V _{SS}	2.5 to 3.6	-15				
	I _{IL} (5)	P87 small signal input side	V _{IN} =VBIS-0.5V (VBIS: Bias voltage)	2.5 to 3.6	-10	-5.5	-1.5		

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Continued from preceding page.

Parameter	Symbol	Pin/Remarks	Conditions			Specific	ation	
i arameter	Gyiriboi	1 III/I CIII alks		V _{DD} [V]	min	typ	max	unit
High level output	V _{OH} (1)	Ports 0, 1, 32 to 35	I _{OH} =-0.4mA	2.5 to 3.6	V _{DD} -0.4			
voltage	V _{OH} (2)	Ports 30, 31	I _{OH} =-1.6mA	2.5 to 3.6	V _{DD} -0.4			
	V _{OH} (3)	Ports 71 to 73	I _{OH} =-0.4mA	2.5 to 3.6	V _{DD} -0.4			
	V _{OH} (4)	Ports A, B, C Ports D, E, F	I _{OH} =-0.4mA	2.5 to 3.6	V _{DD} -0.4			
Low level output voltage	V _{OL} (1)	Ports 0, 1, 32 to 35 Ports 30, 31 (PWM function output mode)	I _{OL} =1.6mA	2.5 to 3.6			0.4	
	V _{OL} (2)	Ports 30, 31 (Port function output mode)	I _{OL} =5mA	2.5 to 3.6			0.4	V
	V _{OL} (3)	Ports 7, 8 XT2	I _{OL} =1.6mA	2.5 to 3.6			0.4	
	V _{OL} (4)	Ports A, B, C Ports D, E, F	I _{OL} =1.6mA	2.5 to 3.6			0.4	2/6
LCD output voltage regulation	VODLS	S0 to S53	I _O =0mA VLCD, 2/3VLCD, 1/3VLCD level output See Fig. 8.	2.5 to 3.6	0	N	±0.2	
	VODLC	COM0 to COM3	IO=0mA VLCD, 2/3VLCD, 1/2VLCD, 1/3VLCD level output See Fig. 8.	2.5 to 3.6	Po	ni	±0.2	
LCD bias resistor	RLCD(1)	Resistance per one bias resister	See Fig. 8.	2.5 to 3.6	42	60		
	RLCD(2)	Resistance per one bias resister 1/2R mode	See Fig. 8.	2.5 to 3.6	DRIV	30		kΩ
Resistance of pull-up MOS Tr.	Rpu(1)	Ports 0, 1, 3, 7 Ports A, B, C, D, E,	A ^{OH=0} a∧ ^{DD}	2.5 to 3.6	18	50	50	
Hysterisis voltage	VHYS(1)	Ports 1, 7	MILEFO	2.5 to 3.6		0.1V _{DD}		V
	VHYS(2)	P87 small signal input side	COLINA	2.5 to 3.6		0.1V _{DD}		V
Pin capacitance	СР	All pins	For pil's other than that under test: V'N=VSS f=1MHz Ta=25°C	2.5 to 3.6		10		pF
Input sensitivity	Vsen	P87 small signal		2.5 to 3.6	0.12V _{DD}			Vpp

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Serial I/O Characteristics at Ta = -40° C to $+85^{\circ}$ C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V, $0.190 \mu s \le tCYC \le 200 \mu s$ SIO0 Serial I/O Characteristics (Note 4-1-1) at V_{DD} = 2.7 V to 3.6V, 0.190 $\mu s \le tCYC \le 200 \mu s$

	Parameter Symbol Pin			Pin/Remarks	Conditions			Specif	ication	
	Г	arameter	Symbol	Fill/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	See Fig. 6.		2			
	¥	Low level pulse width	tSCKL(1)				1			
	Input clock	High level pulse width	tSCKH(1)			2.5 to 3.6	1			
clock	Inl		tSCKHA(1)		Continuous data transmission/reception mode See Fig. 6. (Note 4-1-2)		4			tCYC
Serial clock		Frequency	tSCK(2)	SCK0(P12)	CMOS output selected See Fig. 6.		4/3			
	ck	Low level pulse width	tSCKL(2)		-			1/2		~\C
	Output clock	High level pulse width	tSCKH(2)			2.5 to 3.6		1/2	OF	ιsCK
	O		tSCKHA(2)		Continuous data transmission/reception mode CMOS output selected See Fig. 6.	V	tSCKH(2) +2tCYC	EV	SCKH(2) +(10/3) tCYC	tCYC
nput	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of SIOCLK.	· OF	0.03		NO	
Serial input	Da	ta hold time	thDI(1)		• See Fig. 6.	2.5 to 3.6	0.03	MA		
	lock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmissio. /reception mode (Note 4 1-3)	MF	O,		(1/3)tCYC +0.05	μS
Serial output	Input clock		tdD0(2)		Syn chronous 8-bit mode Note 4-1-3)	2.5 to 3.6			1tCYC +0.05	,
Seri	Output clock		tdD0(3)	NOT	(Note 4.1-3)				(1/3)tCYC +0.05	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SI0RUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of

output state change in open drain output mode. See Fig. 6.

SIO1 Serial I/O Characteristics (Note 4-2-1)

	-)	O. wash all	Dia/Dassadas	Consultation of			Specifi	cation	
	-	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	ж	Frequency	tSCK(3)	SCK1(P15)	See Fig. 6.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.5 to 3.6	1			tCYC
Serial clock	In	High level pulse width	tSCKH(3)				1			TOYC
Serial	ock	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected See Fig. 6.		2			
	Output clock	Low level pulse width	tSCKL(4)			2.5 to 3.6		1/2		tSCK
	Õ	High level pulse width	tSCKH(4)					1/2		ISON
Serial input	Da	ta setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK.	2.5 to 3.6	0.03			-(G)
Seria	Da	ta hold time	thDI(2)		• See Fig. 6.	2.5 to 3.6	0.03		OE	5
put	Ou	tput delay time	tdD0(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK.			JEV	7	μs
Serial output					Must be specified as the time to the beginning of output state change in open drain output mode.	2.5 to 3.6	OF	emi	(1/3)tCYC ; 0 U5	
					• See Fig. 6.		04,2	100		

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Doromotor	Cumbal	Din/Danyarka				Spec	ification	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low	tPIH(1)	INT0(P70),	• Ir terrupt source (lagran be set.					
level pulse	tPIL(1)	INT1(P71),	Event inputs for timer 0 or 1 are					
width		INT2(P72),	enabled.					
		INT4(P30 to P33).	17 M	2.5 to 3.6	1			
		INT5(P34 to P35),	17					
	11(INT6(P30),						
Y .		INT7(P34)						
	tPIH(2)	INT3(P73) when noise filter	 Interrupt source flag can be set. 	2.5 to 3.6	2			tCYC
	tPIL(2)	time constant is 1/1	• Event inputs for timer 0 are enabled.	2.3 10 3.0	2			ĺ
115	tPIH(3)	INT3(P73) when noise filter	 Interrupt source flag can be set. 	2.5 to 3.6	64			
	tPIL(3)	time constant is 1/32	• Event inputs for timer 0 are enabled.	2.5 10 5.0	04			
	tPIH(4)	INT3(P73) when noise filter	 Interrupt source flag can be set. 	2.5 to 3.6	256			
	tPIL(4)	time constant is 1/128	• Event inputs for timer 0 are enabled.	2.5 10 5.0	230			
	tPIH(5)	MICIN(P87)	Condition that signal is accepted to	2.5 to 3.6	1			
	tPIL(5)		small signal detection counter.	2.5 10 5.0	!			
	tPIH(6)	RMIN(P73)	Condition that signal is accepted to	2.5 to 3.6	4			RMCK
	tPIL(6)		remote control receiver circuit.	2.0 10 3.0	4			(Note 5-1)
	tPIL(7)	RES	Resetting is enabled.	2.5 to 3.6	200			μS

Note 5-1: RMCK is an unit for the base clock (40tCYC/50tCYC/Sub-Clock) of remote control receiver circuit.

AD Converter Characteristics at $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

<12bits AD Converter Mode at Ta =-30 to +70°C>

	0	D: /D	0 - 1111			Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P80) to		2.5 to 3.6		12		bit
Absolute accuracy	ET	AN7(P87), AN8(P70),	(Note 6-1)	2.5 to 3.6			±16	LSB
Conversion	tCAD	AN9(P71),	See Conversion time calculation	3.0 to 3.6	64		115	
time		AN10(XT1), AN11(XT2)	formulas.	2.7 to 3.6	128		230	μS
		ANTI(X12)	(Note 6-2)	2.5 to 3.6	256		460	
Analog input voltage range	VAIN				V _{SS}		V _{DD}	V
Analog port	IAINH		VAIN=V _{DD}	2.5 to 3.6			1	
input current	IAINL		VAIN=V _{SS}		-1			μΑ

<8bits AD Converter Mode at Ta =-30 to +70°C>

Parameter	O make al	Pin/Remarks	Conditions			Specification	2)
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min t	yp ma t	unit
Resolution	N	AN0(P80) to		2.5 to 3.6		8	bit
Absolute accuracy	ET	AN7(P87), AN8(P70),	(Note 6-1)	2.5 to 3.6	MI	±1.5	LSB
Conversion time	TCAD	AN9(P71), AN10(XT1), AN11(XT2)	See Conversion time calculation formulas. (Note 6-2)	3.0 to 3.6 2.7 to 3.6 2.5 to 3.6	39 79	71 140 280	μs
Analog input voltage range	VAIN			0	V _{SS}	V _{DD}	٧
Analog port	IAINH		VAIN=V _{DD}	2.5 to 3.6	(5/1)	1	•
input current	IAINL		VAIN=V _{SS}	2.5 to 3.6	-1		μА

<Conversion time calculation formulas>

12bits AD Converter Mode: tCAD Conversion time)= $((52/(\text{civision ratio})) + 2) \times (1/3) \times \text{tCYC}$ 8bits AD Converter Mode: tCAD(Conversion time)= $((32/(\text{division ratio})) + 2) \times (1/3) \times \text{tCYC}$

- Note 6-1: The quantization error ($\pm 1/21$ SB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.
- Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Consumption Current Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Normal mode	Doron	Company of	Pin/	Condition			Specifi	cation	
Normal mode	Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
FmX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal RC oscillation stopped. Frequency variable RC oscillation stopped. IDDOP(3) IDDOP(3) FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation Frequency variable RC oscillation stopped. IDDOP(4) IDDOP(4) IDDOP(4) IDDOP(4) IDDOP(5) IDDOP(5) IDDOP(6) FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped. System clock set to 10MHz with frequency variable RC oscillation IDDOP(5) IDDOP(6) IDDOP(7) IDDOP(7) IDDOP(8) ID	consumption current	IDDOP(1)	=V _{DD} 2	FmX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal RC oscillation stopped. Frequency variable RC oscillation stopped.	2.7 to 3.6		6.1	15.6	
FmX'tal=32.768kHz crystal oscillation mode		IDDOP(2)		FmX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal RC oscillation stopped. Frequency variable RC oscillation stopped.	2.5 to 3.6		3.9	8.8	-
FmX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped. System clock set to 10MHz with frequency variable RC oscillation 1/1 frequency division retio FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode Internal RC escillation stopped. System clock set to 4MHz with frequency variable RC oscillation 1/1 frequency division ratio System clock set to 4MHz with frequency variable RC oscillation FmX (al=32.768kHz crystal oscillation mode) FmX (al=32.768kHz crystal oscillation mode) System clock set to 32.768kHz side Internal RC oscillation stopped. 19.3 73		IDDOP(3)		FmX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation Frequency variable RC oscillation stopped.	2.5 to 3.6		0.4	1.7	m.
IDDOP(5) • FmCF=0Hz (oscillation stopped) • FmX'tal=32.768kHz c ystal oscillation mode • Internal RC oscillation stopped. • System clock set to 4MHz with frequency variable RC oscillation • 1/1 frequency division ratio • FmC ==0Hz (oscillation stopped) • FmX':al=32.768kHz systal oscillation mode • system clock set to 32.768kHz side • Internal PC oscillation stopped.		IDDOP(4)		FmX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped. System clock set to 10MHz with frequency variable RC oscillation	2.5 to 3.6	RI	4.3	12.0	
IDDOP(6) • FmC = 0Hz (oscillation stopped) • FmC al=32.768 kHz rystal oscillation mode • System clock set to 32.768 kHz side • Internal PC oscillation stopped. 19.3 73		IDDOP(5)		FmCF=0Hz (oscillation stopped) FmX'tal=32.768xHz crystal oscillation mode Internal RC oscillation stopped. System clock set to 4MHz with frequency variable RC oscillation.	2.5 to 3.6	nse Pl	2.1	6.6	-
• 1/2 frequency d vision ratio		IDDOP(6)		Fm \(a = 32.768 \text{iHz} \) brystal cscillation mode System clock set to 32.768 \text{iHz} \) side Internal PC oscillation stopped. Frequency variable RC oscillation stopped.	2.5 to 3.6		19.3	73	μА

Continued from preceding page.

Parameter	Symbol	Pin/	Conditions			Specif	ication	
		Remarks		V _{DD} [V]	min	typ	max	unit
HALT mode consumption current (Note 7-1)	IDDHALT(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	HALT mode FmCF=18MHz ceramic oscillation mode FmX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.7 to 3.6		2.7	6.8	
	IDDHALT(2)		HALT mode FmCF=8MHz ceramic oscillation mode FmX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal RC oscillation stopped. Frequency variable RC oscillation stopped.	2.5 to 3.6		1.4	3.1	
	IDDHALT(3)		HALT mode FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation Frequency variable RC oscillation stopped. 1/2 frequency division ratio	2.5 to 3.6		0.2	0.75	S _{mA}
	IDDHALT(4)		HALT mode FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal escillation mode Internal RC oscillation stopped. System clock set to 10MHz with frequency variable RC oscillation. 1/1 frequency division ratio	2.5 to 3.6	R	1.6	4.6	
	IDDHALT(5)		HALT mode FmCF=UHz (oscillation stopped) FmX tal=32,768kHz crystal oscillation mode Internal RC oscillation stopped System clock set to 4MHz vith frequency variable RC oscillation 1/1 frequency division ratio	2.5 to 3.6	PI	0.7	1.75	
0	IDDHALT(6)	SNIC	HALT mod FMCF -0Hz (uscillation stopped) FMCF -0Hz (uscillation stopped) FMC - 0Hz (uscillation stopped) FMC - 0Hz - 0H	2.5 to 3.6		12.4	54.9	
HOLD mode consumption	IDDHOLD(1)	V _{DD}	HOLD mode CF1=V _{DD} or open (External clock mode)	2.5 to 3.6		0.08	18.4	μА
Timer HOLD mode consumption current	IDDHOLD(2)		Timer HOLD mode CF1=V _{DD} or open (External clock mode) FmX'tal=32.768kHz crystal oscillation mode	2.5 to 3.6		10.14	34.4	

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

F-ROM Write Characteristics at Ta = +10°C to +55°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V

Danamatan	Symbol Pin/Remarks Conditions						Specification			
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit		
Onboard programming current	IDDFW(1)	V _{DD} 1	Without CPU current	3.0 to 3.6		7	11	mA		
Programming	tFW(1)		2K-byte erase operation	3.0 to 3.6		12	15	ms		
time	tFW(2)		2K-byte writing operation	3.0 to 3.6		35	45	μS		

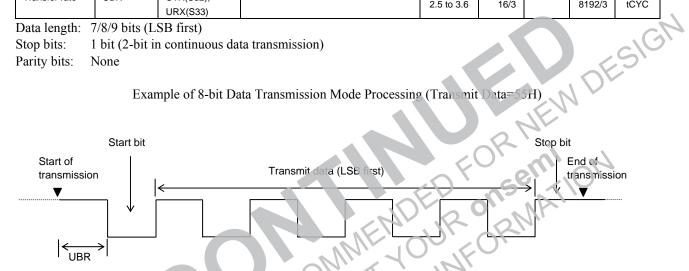
UART (Full Duplex) Operating Conditions at Ta = +40 to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Danamatan	0	Di /D		Specification			ication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Transfer rate	UBR	UTX(S32),		2.5 to 3.6	16/3		8192/3	tCYC
		URX(S33)		2.5 (0 3.6	10/3		0192/3	icrc

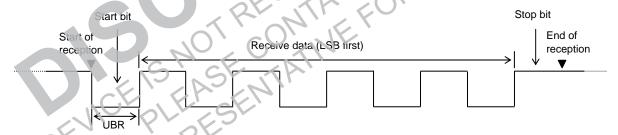
Data length: 7/8/9 bits (LSB first)

1 bit (2-bit in continuous data transmission) Stop bits:

Parity bits: None



Example of 8-bit Data Reception Mode Processing (Receive Data=55H)



Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

Nominal	Vendor	Oscillator Name		Circuit (Constant		Operating Voltage	Stabil	lation ization me	Remarks
Frequency Name			C1 [pF]	C2 [pF]	Rf1 [Ω]	Rd1 [Ω]	Range [V]	typ [ms]	max [ms]	
400411	MUDATA	CSTCE18M0V51-R0	(5)	(5)	OPEN	150	2.7 to 3.6	0.05	0.15	Values shown in parentheses
18MHz	MURATA	CSTLS18M0X51-B0	(5)	(5)	OPEN	0	2.7 to 3.6	0.11	0.33	are capacitance included in the oscillator
400411-	MUDATA	CSTCE10M00G52-R0	(10)	(10)	OPEN	680	2.5 to 3.6	0.05	0.15	Values shown in parentheses are capacitance included
10MHz	MURATA	CSTLS10M00G53-B0	(15)	(15)	OPEN	1.5k	2.5 to 3.6	0.05	0.15	in the oscillator
ONAL I—	MURATA	CSTCE8M00G52-R0	(10)	(10)	OPEN	680	2.5 to 3.6	0.05	0.15	Values shown in parentheses are capacitance included
8MHz	WURATA	CSTLS8M00G53-B0	(15)	(15)	OPEN	1.5k	2.5 to 3.6	0.05	0.15	n the oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 4).

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillation Circuit with a Crystal Oscillation

Nominal	Vander Neme	Oscillator		Circuit (Constant	N	Operating Voltage	(2)	!⊱tion tion Time	Domorko
Frequency	Vendor Name	Name	C3 [pF]	C4 [pF]	Rí2 [Ω]	Rd2 [Ω]	Range [V]	typ [s]	max [s]	Remarks
32.768kHz	EPSON TOYOCOM	MC-306	9	99	Open	330k	2.5 to 3.6	1.0	3.0	CL=7.0pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HCLD mode is reset (see Fig. 4).

Caution: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

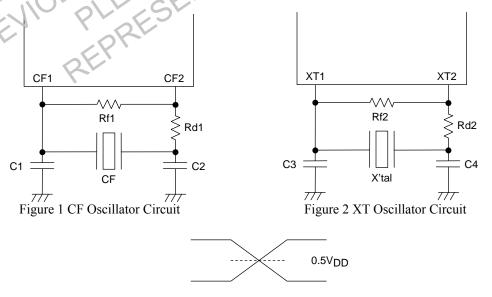
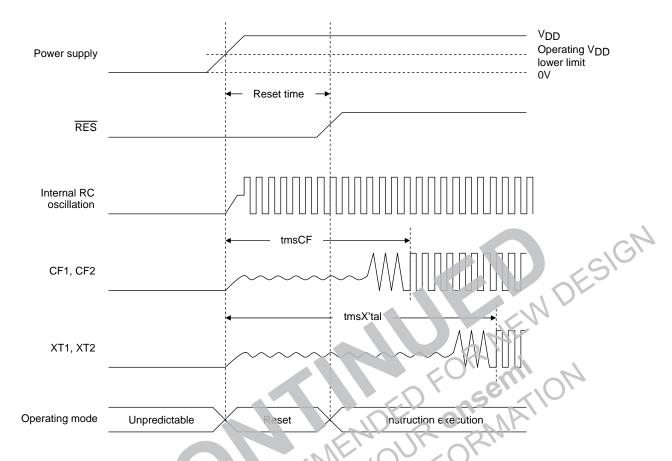
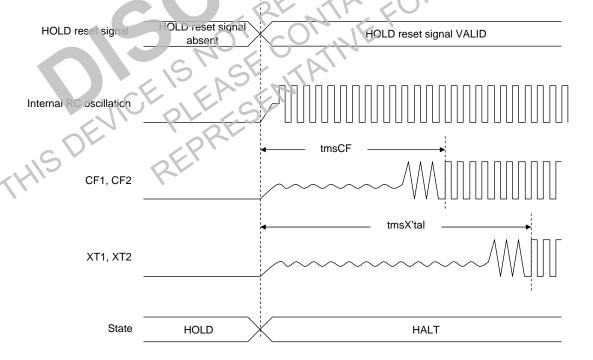


Figure 3 AC Timing Measurement Point

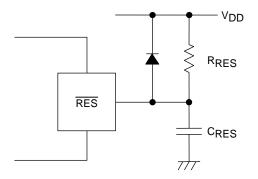


Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Times



Note:

Determine the value of CRES and RRES so that the reset signal is present for a period of $200\mu s$ after the supply voltage goes beyond the lower limit of the IC's operating voltage.

Figure 5 Reset Circuit

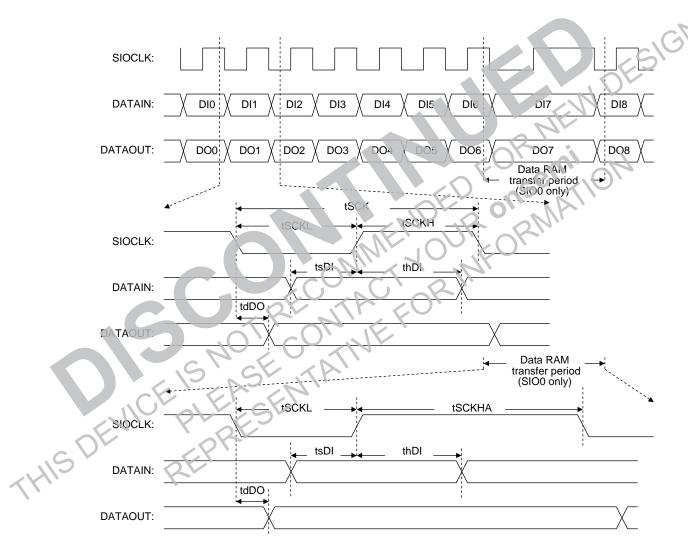


Figure 6 Serial I/O Waveforms

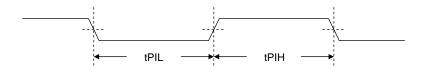
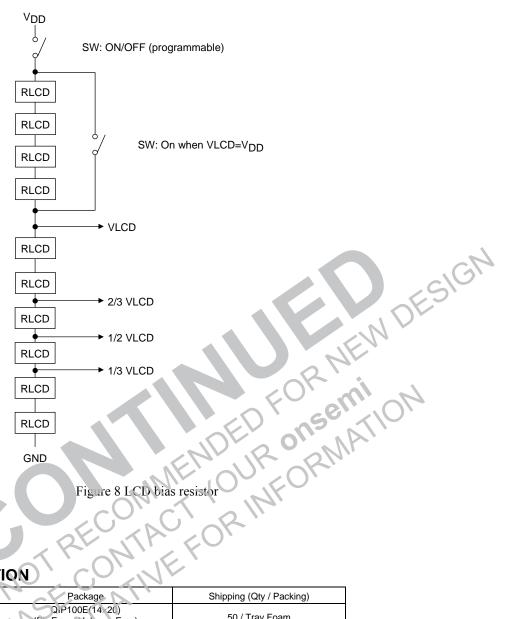


Figure 7 Pulse Input Timing Signal Waveform



ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
LC87F7NC8AUEJ-2H	QiP100E(14.⁄20) (Pb-Free / Halogen Free)	50 / Tray Foam
LC87F7N SAVUEJ-2H	QIP100E(14×20) (Pb Free / Halogen Free)	50 / Tray Foam
THIS DE	REPRE	

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